

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Complete Listing of Claims:

1. (Currently Amended) A high copper alloy having consisting, by weight, essentially of:
from 0.8% to 3% of iron;
from 0.3% to 2% of nickel;
from 0.6% to 1.4% of tin;
from 0.005% to 0.35% of phosphorous;
less than 0.2% of zinc; and
the balance copper and inevitable impurities, said copper alloy having a relief anneal temper commensurate with having been formed at a temperature of about 200°C to 350°C for about 30 minutes to 6 hours, having resistance to stress relaxation at elevated temperatures superior to copper alloy C19500[;], having an ultimate tensile strength in excess of 70 ksi[;], and having an electrical conductivity in excess of 40% IACS.
2. (Original) The copper alloy of claim 1 wherein said iron is present in an amount of from 1% to 2%.
3. (Original) The copper alloy of claim 2 wherein said iron is present in an amount of from 1% to 1.5%.
4. (Original) The copper alloy of claim 2 wherein said nickel is present in an amount of from 0.5% to 1.3%.
5. (Original) The copper alloy of claim 4 wherein said nickel is present in an amount of from 0.5% to 1%.
6. (Original) The copper alloy of claim 4 wherein said tin is present in an amount of from 0.7% to 1.1%.

7. (Original) The copper alloy of claim 6 wherein said tin is present in an amount of from 0.8% to 1%.

8. (Original) The copper alloy of claim 6 wherein said phosphorous is present in an amount of from 0.01% to 0.1%.

9. (Original) The copper alloy of claim 8 being formed into an electrical connector.

10. (Previously Presented) The copper alloy of claim 1 consisting, by weight, essentially of:

- from 1% to 1.5% of iron;
- from 0.5% to 1% of nickel;
- from 0.8% to 1% of tin;
- from 0.01% to 0.1% of phosphorous;
- less than 0.2% of zinc; and
- the balance copper and inevitable impurities.

11. (Previously Presented) The copper alloy of claim 10 formed into an electrical connector.

Claims 12 – 24 (Cancelled)

25. (New) The copper alloy of claim 1 wherein said relief anneal temper is formed at a temperature of about 250°C to 320°C for about 1 to 3 hours.